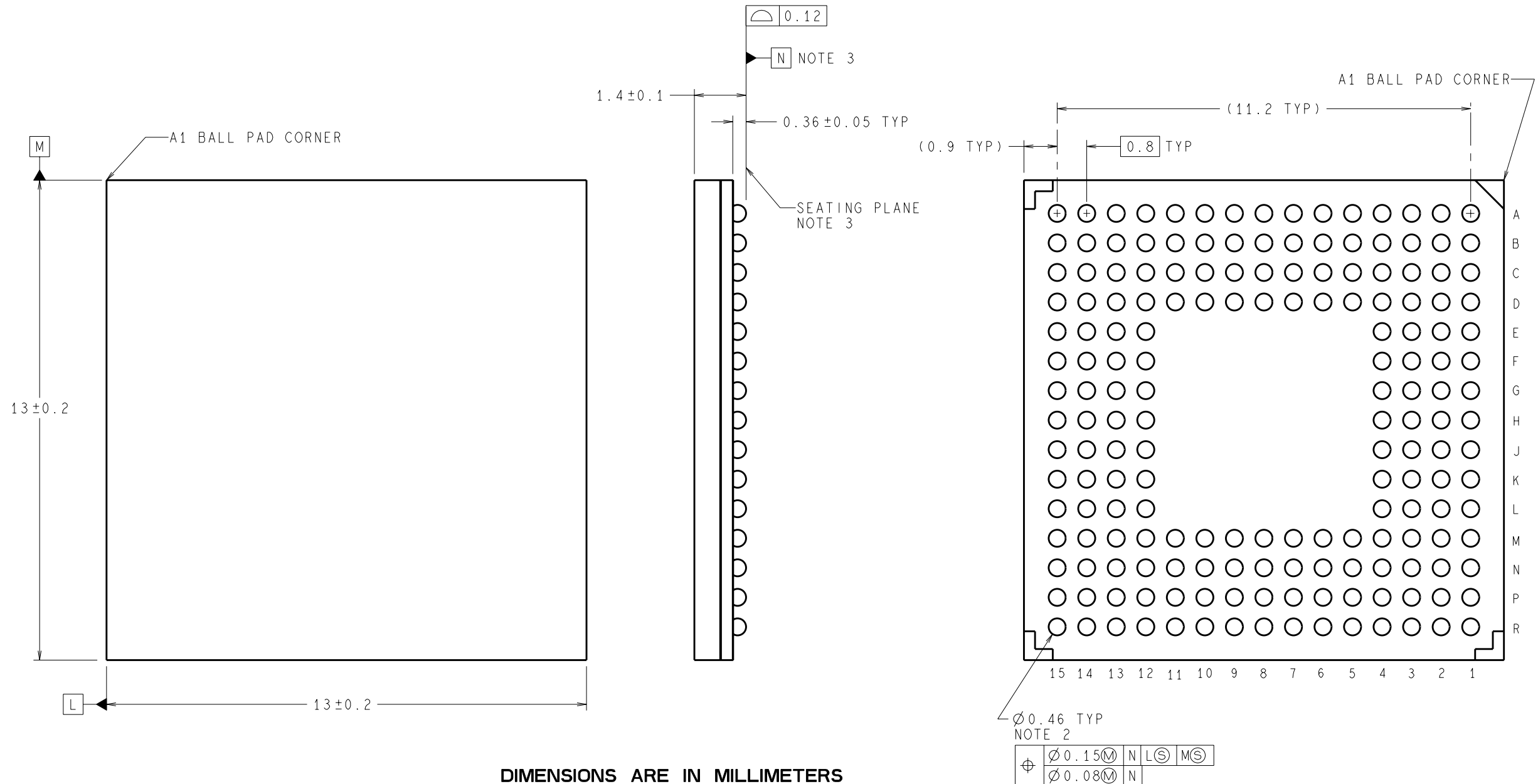


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	160	09/08/2000	TL/JF



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. NO JEDEC REGISTRATION AS OF SEPTEMBER 2000.

APPROVALS		DATE	National Semiconductor		
DRAWN T. LEQUANG		09/08/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. MARTA SUCHY		09/08/2000	FBGA, PLASTIC, LAMINATED, 13 X 13 X 1.4mm BODY, 176 BALL, 0.8mm PITCH		
ENGR. CHK. JEFF SCHAEFER		09/08/2000			
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-SLC176A	A
DO NOT SCALE DRAWING				SHEET 1 of 1	